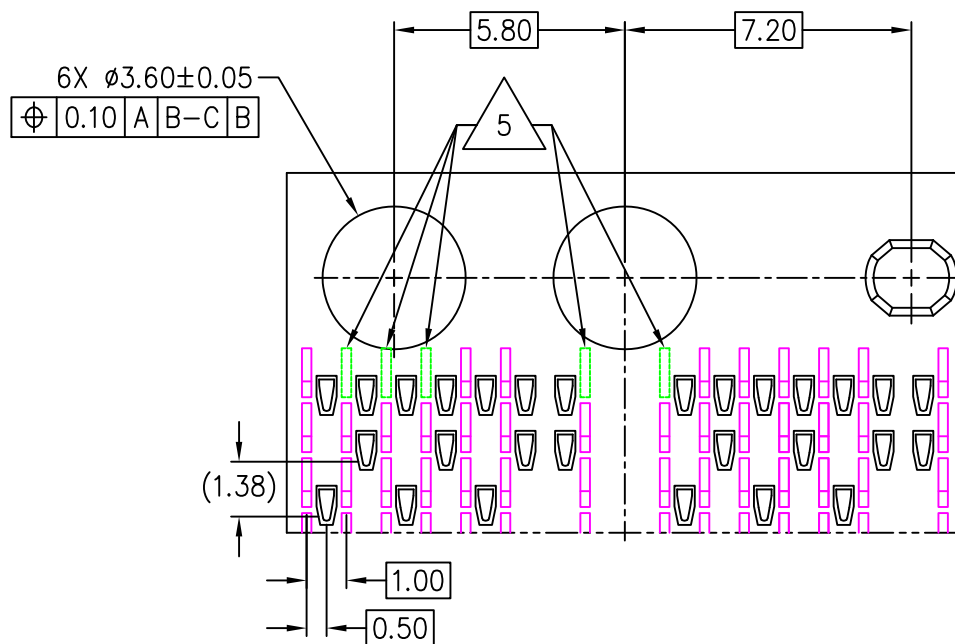
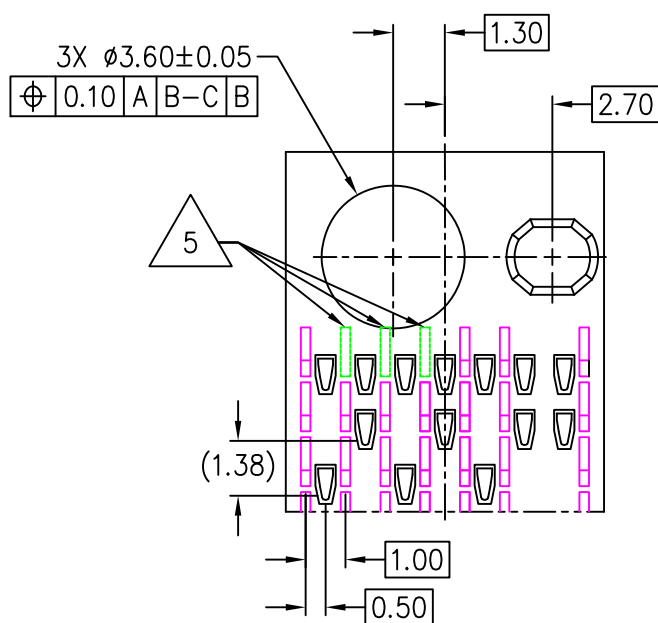


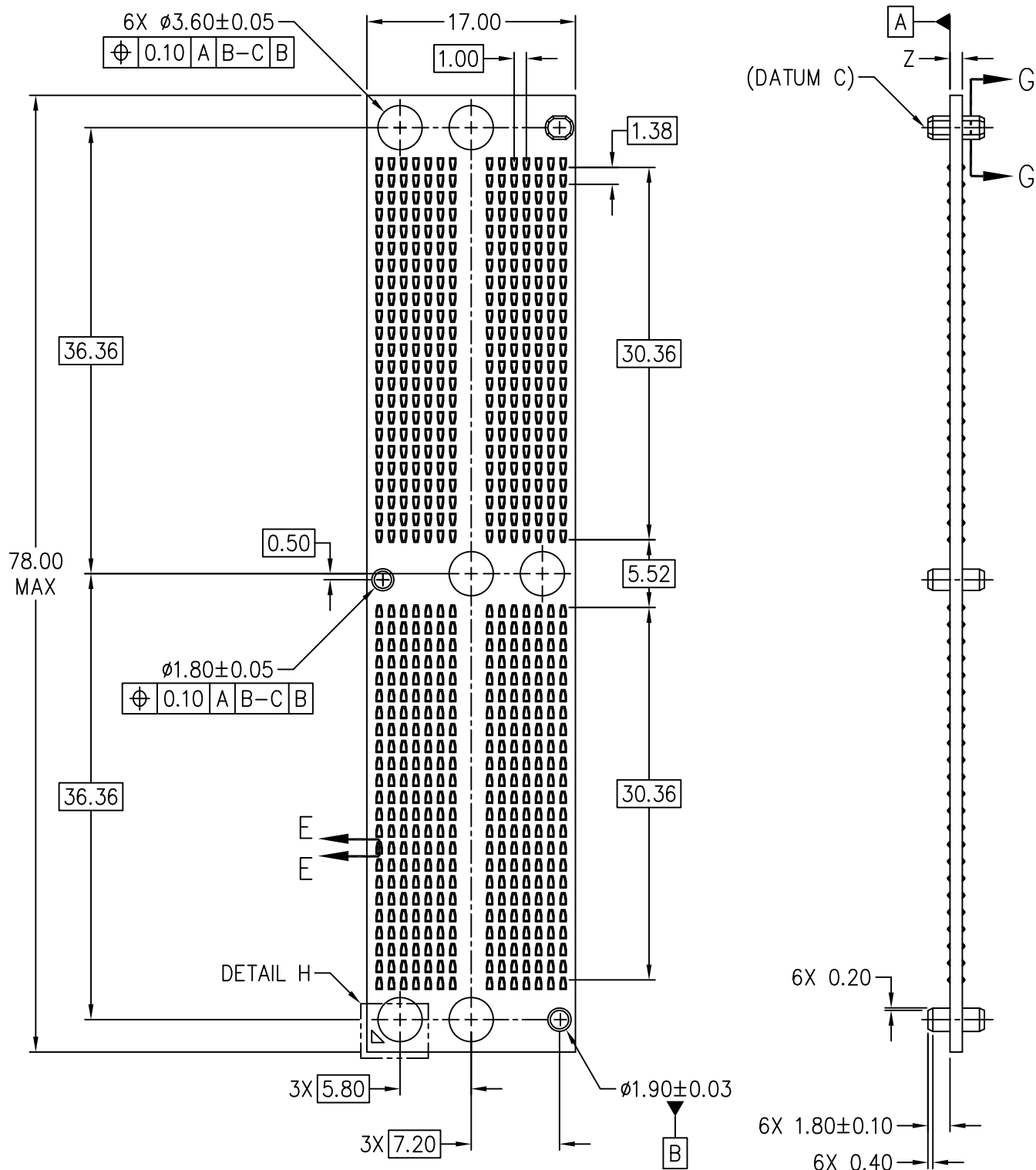
SHEET
2 OF 21



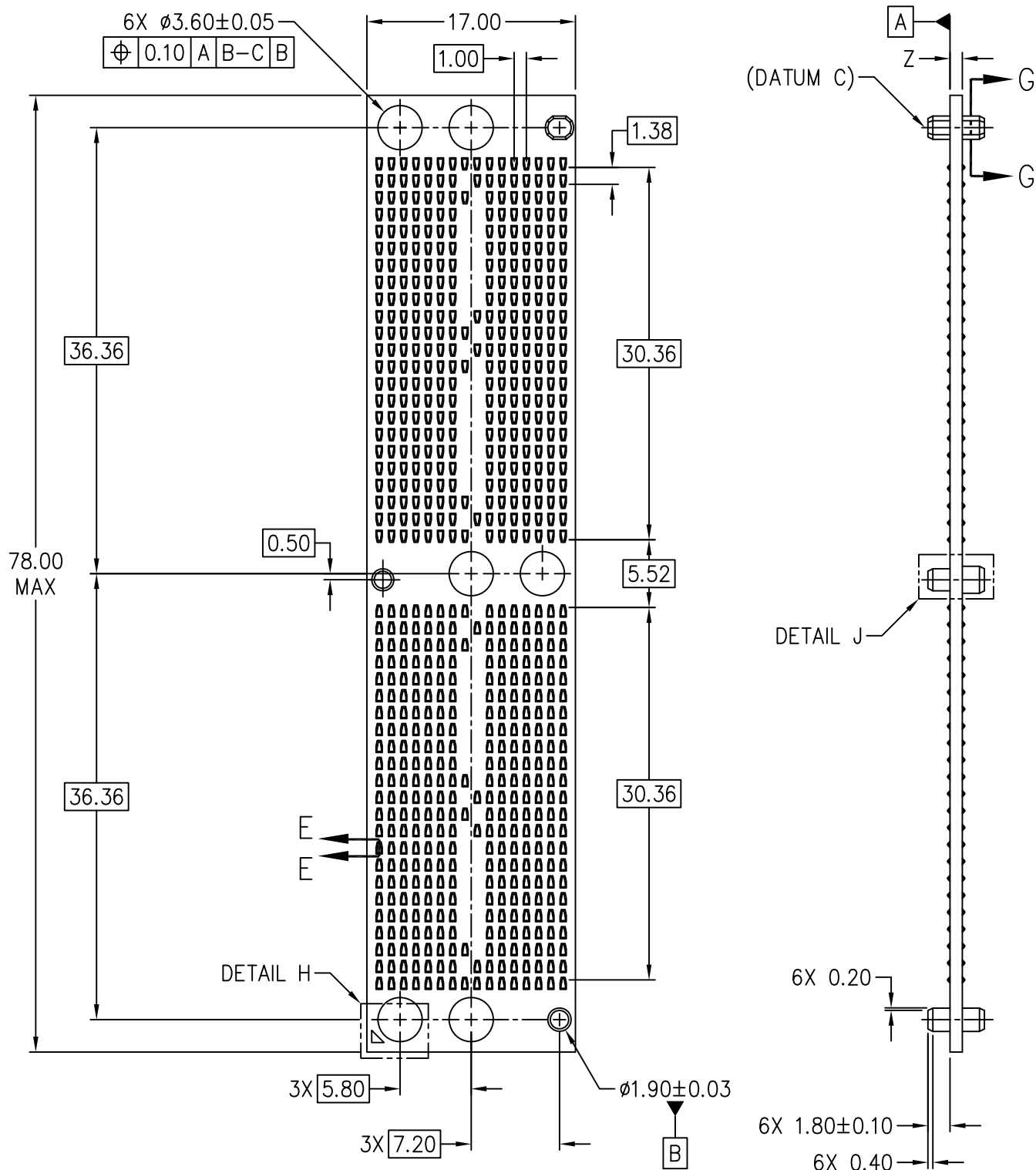
DETAIL A



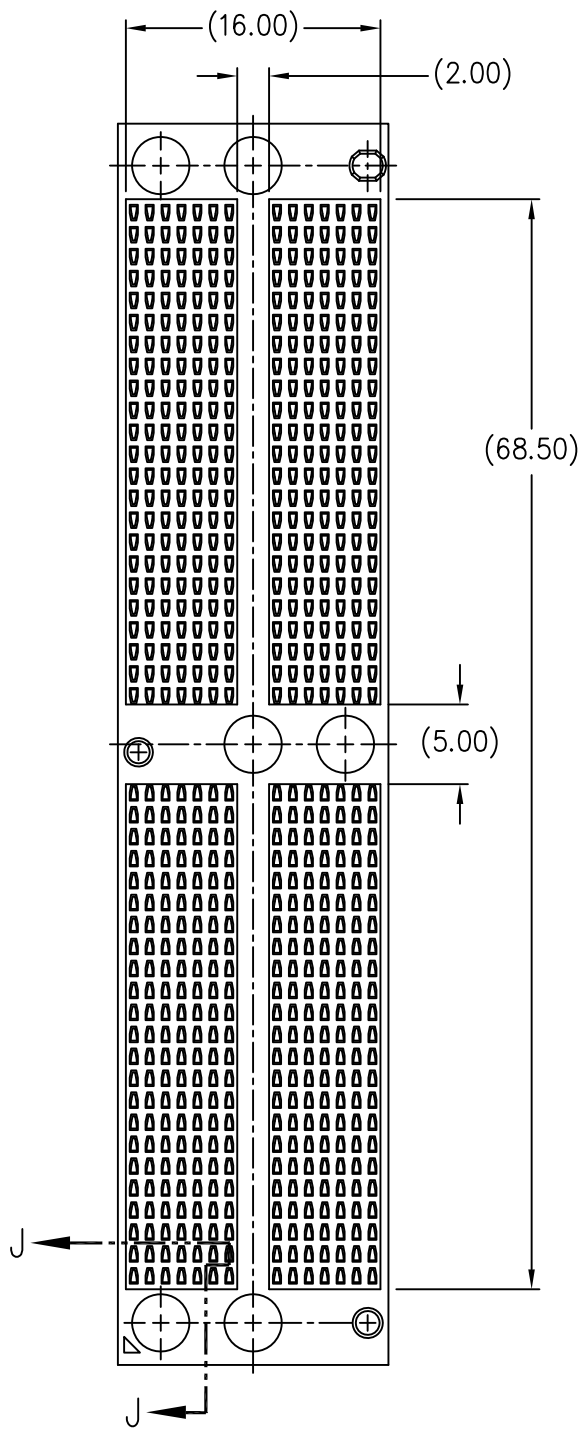
DETAIL B



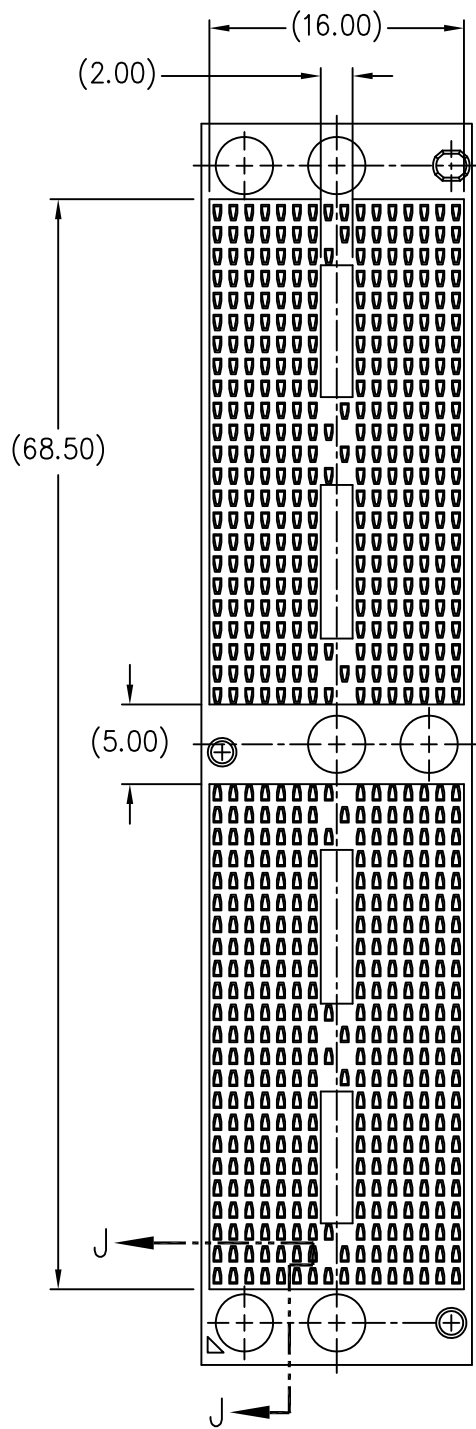
VARIATION: Cxxx



VARIATION: Dxxx

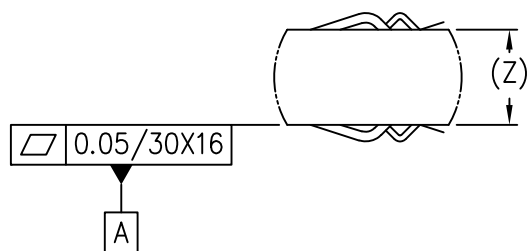


VARIATION: Cxxx

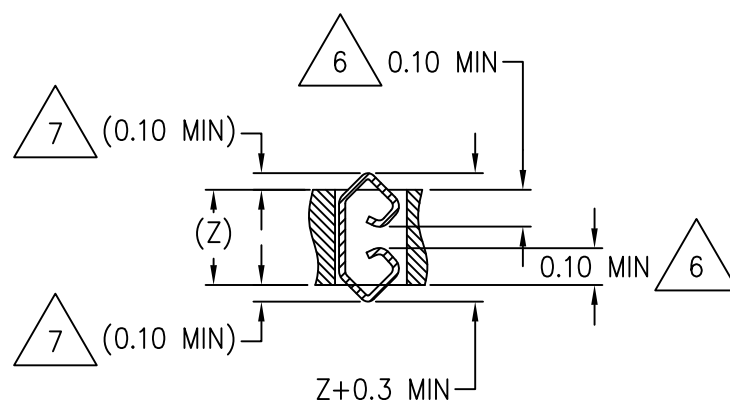


VARIATION: Dxxx

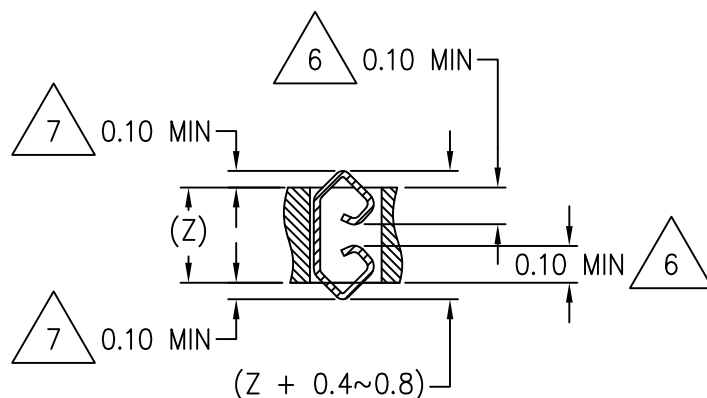
VARIATION: Cxxx AND Dxxx WITH RECOMMENDED
RECESSED CONTACT AREA (OPTIONAL)



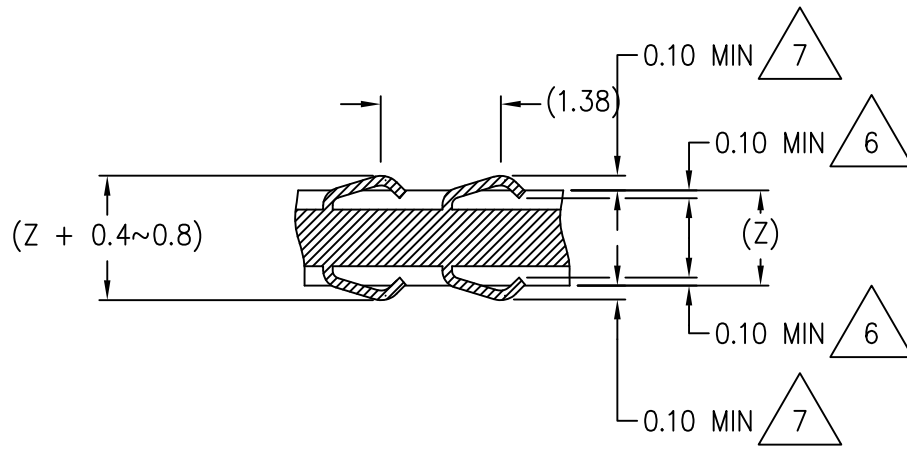
DETAIL D
ROTATE 90 DEGREE CCW



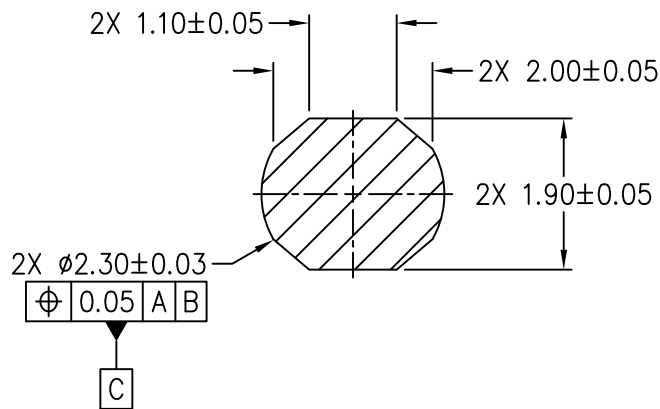
SECTION E – E
FLOATING PIN SHAPE A
ROTATE 90 DEGREE CW



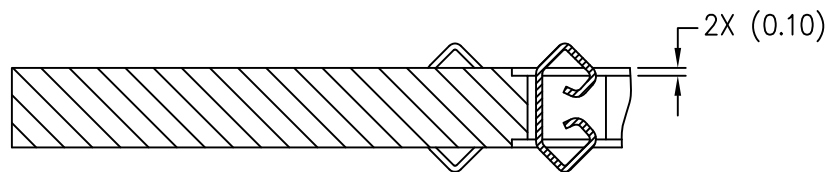
SECTION E – E
LOCKED PIN SHAPE A
ROTATE 90 DEGREE CW



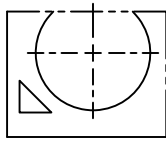
SECTION F – F
PIN SHAPE B
ROTATE 90 DEGREE CCW



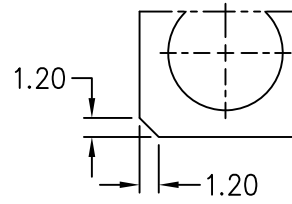
SECTION G – G



SECTION J – J
ROTATE 90 DEGREE CW
(OPTIONAL)

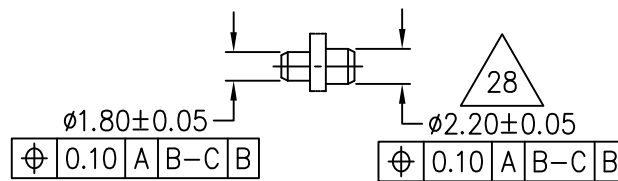


OPTION A



OPTION B

DETAIL H



DETAIL K

TABLE 1

HEIGHT					
VARIATION ►		xAxx	xBxx	xCxx	xDxx
SYMBOL ▼					
Z	MIN	0.95	1.80	2.80	7.45
	NOM	1.00	1.85	2.85	7.50
	MAX	1.05	1.90	2.90	7.55
NOTES		—			
REF		14–215, 14–222			
ISSUE		B			

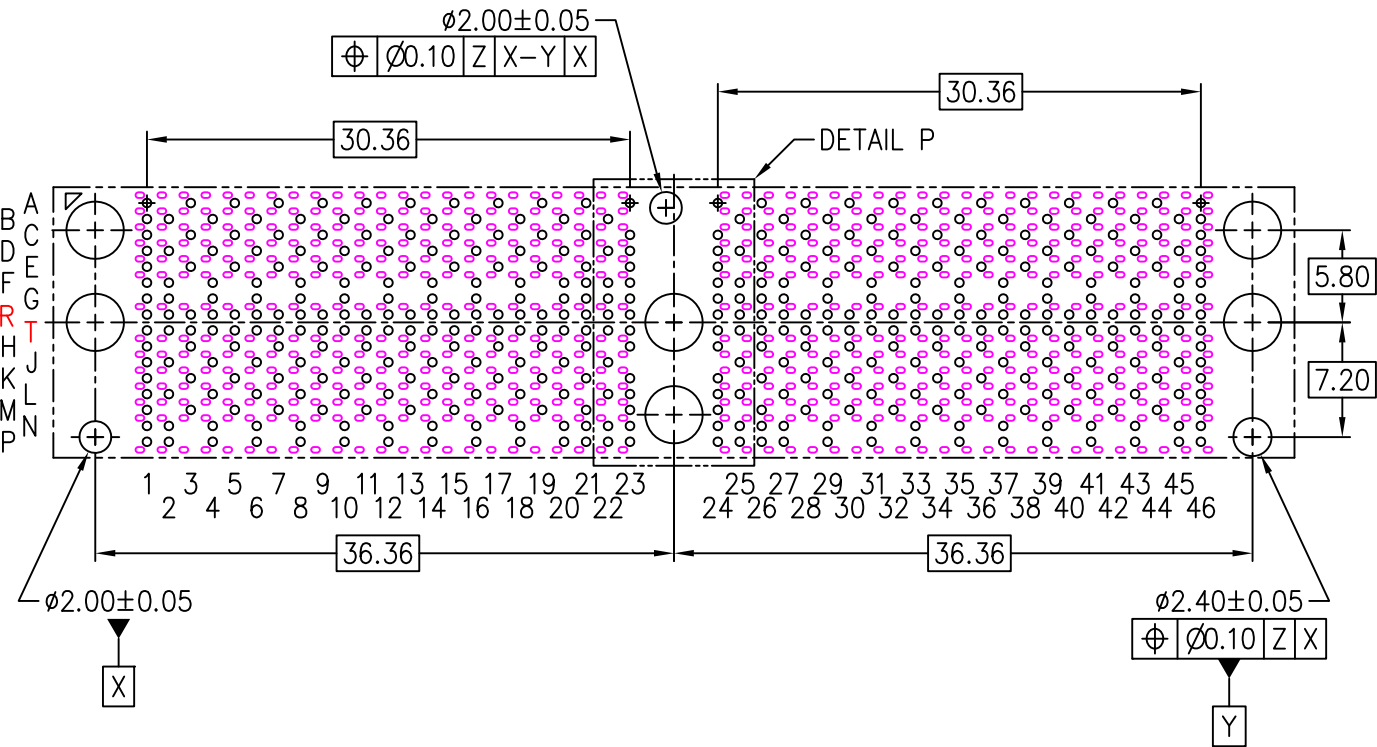
NOTES:

1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5–2009.
2. ALL DIMENSIONS ARE IN MILLIMETERS, TOLERANCES ON ALL DIMENSIONS ± 0.15 UNLESS OTHERWISE SPECIFIED.
3. REFER TO CAMM REGISTERED OUTLINE MO–357 FOR LP5 CAMM2 MODULE DIMENSIONS.
REFER TO CAMM REGISTERED OUTLINE MO–358 FOR LPDDR5 CAMM2 MODULE DIMENSIONS.
4. REFER TO JEDEC PS–007, DDR5/LPDDR5 CAMM CONNECTOR PERFORMANCE STANDARD.

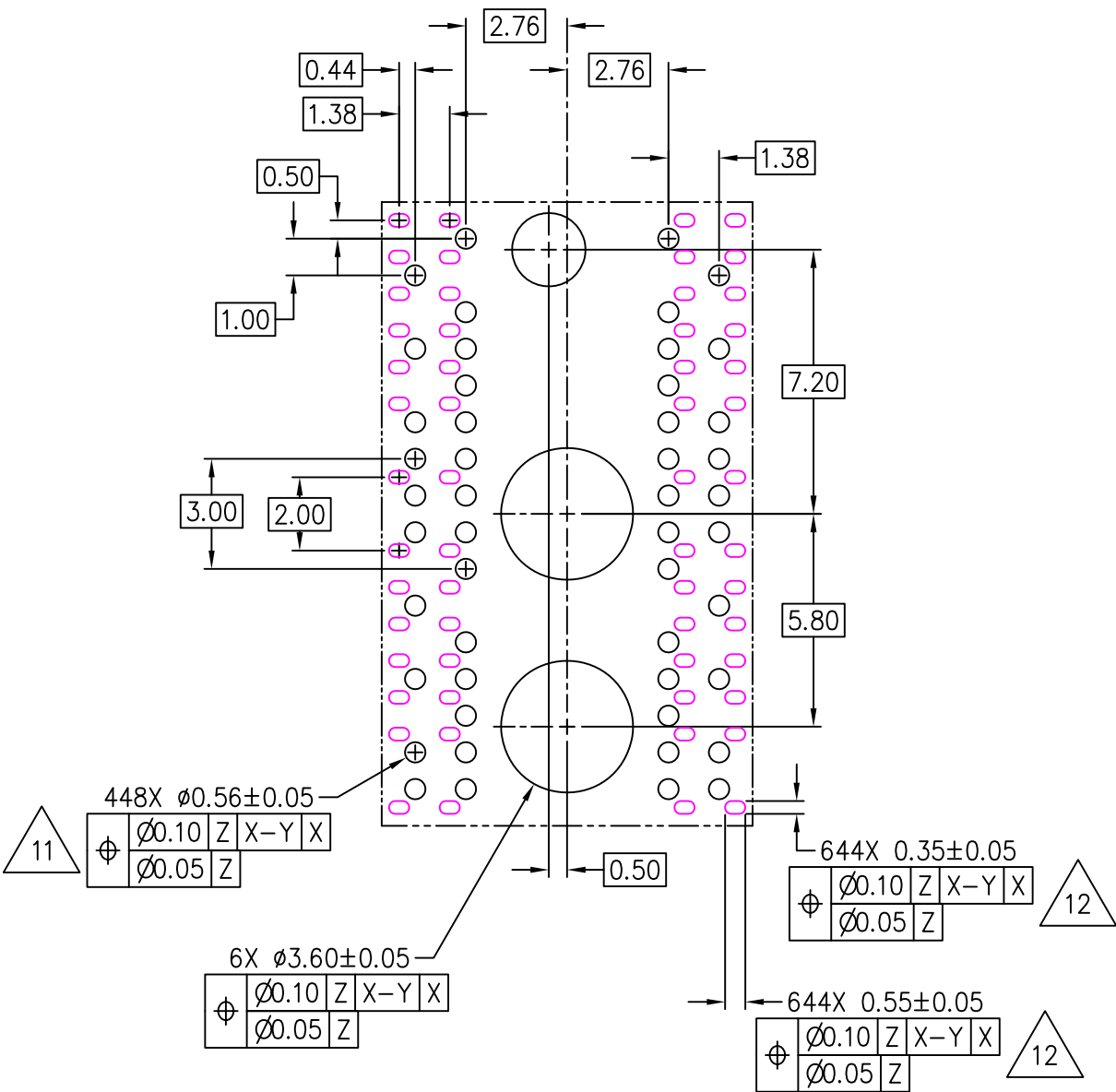
- 5 THESE CONTACTS NEAR THE MOUNTING HOLES ARE ALLOWED TO BE REMOVED DUE TO MANUFACTURING CONCERN.
- 6 THE PIN TIPS ARE BURIED IN THE HOUSING FOR BOTH SIDES.
- 7 THE PIN CONTACT SURFACE ARE EXPOSED OUT OF THE HOUSING FOR BOTH SIDES.
- 8 VARIOUS COMPANIES HAVE ISSUED PATENTS AND RELATED PATENT APPLICATIONS THAT MAY APPLY TO THIS REGISTRATION. IF THE CURRENT ISSUE PATENTS OR LATER PATENTS RESULTING FROM RELATED APPLICATIONS DO APPLY, THESE COMPANIES INTEND TO COMPLY WITH THE JEDEC PATENT POLICY AND LICENSE UNDER REASONABLE TERMS AND CONDITIONS THAT ARE DEMONSTRABLY FREE OF ANY UNFAIR DISCRIMINATION. REFERENCED PATENTS ARE AS FOLLOWS.

AMPHENOL	PATENT NO.: 9,425,525
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9. REFERENCE HOST BOARD FOOTPRINT (APPLY TO VARIATION: Axxx ONLY). CONNECTOR PINS SHALL LAND ON THE PAD BEFORE AND AFTER DEFLECTION DURING THE ASSEMBLY.



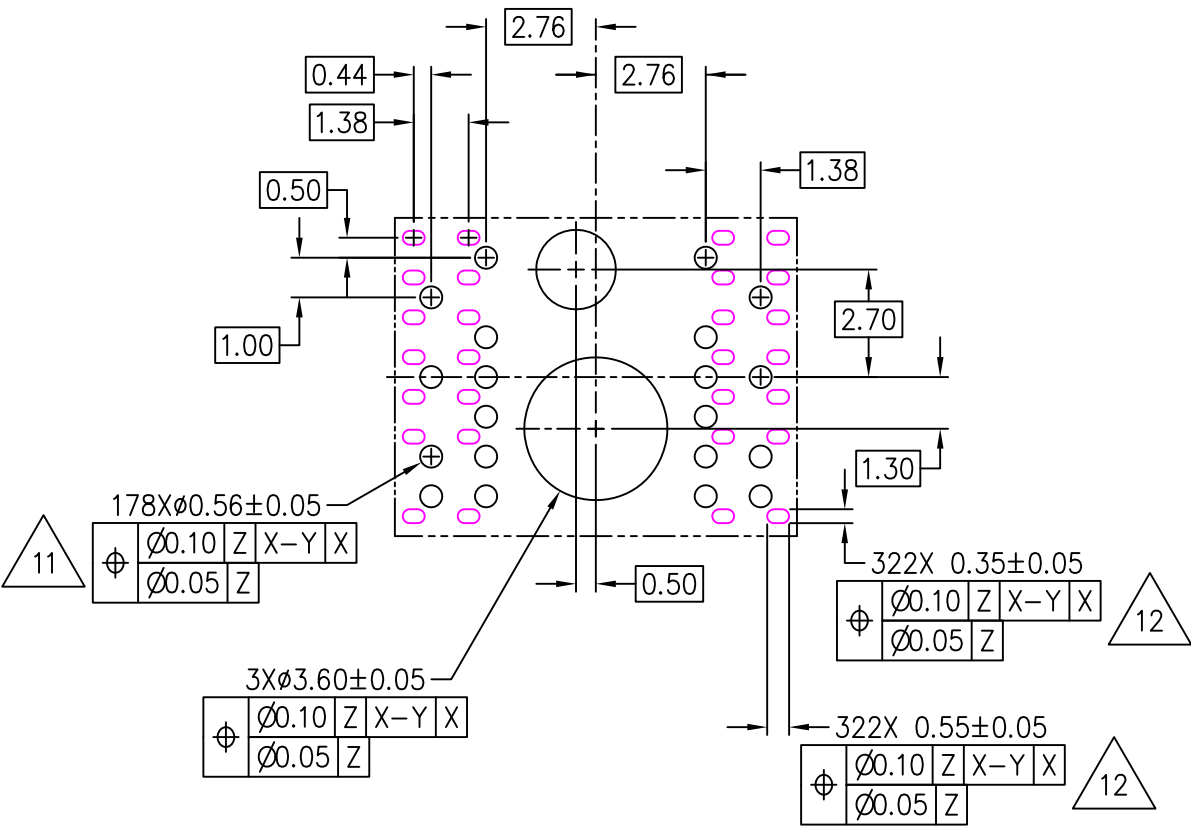
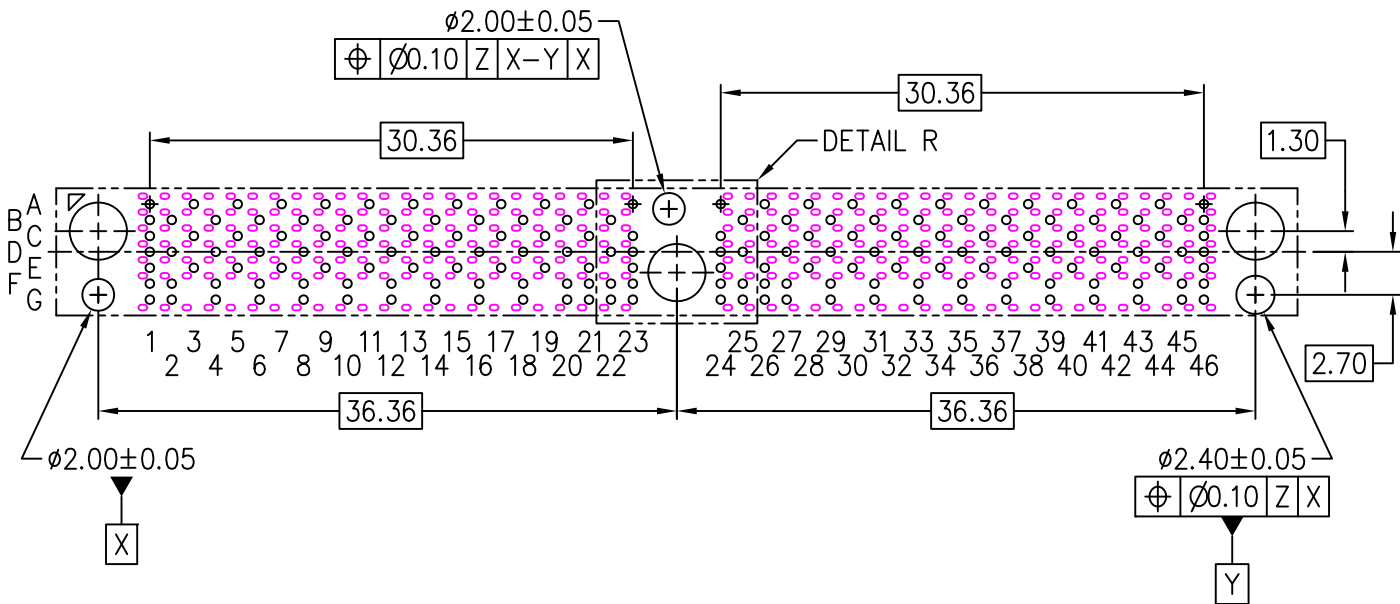
NOTES CONTINUED:





DETAIL P
DATUM Z: HOST BOARD SURFACE

NOTES CONTINUED:

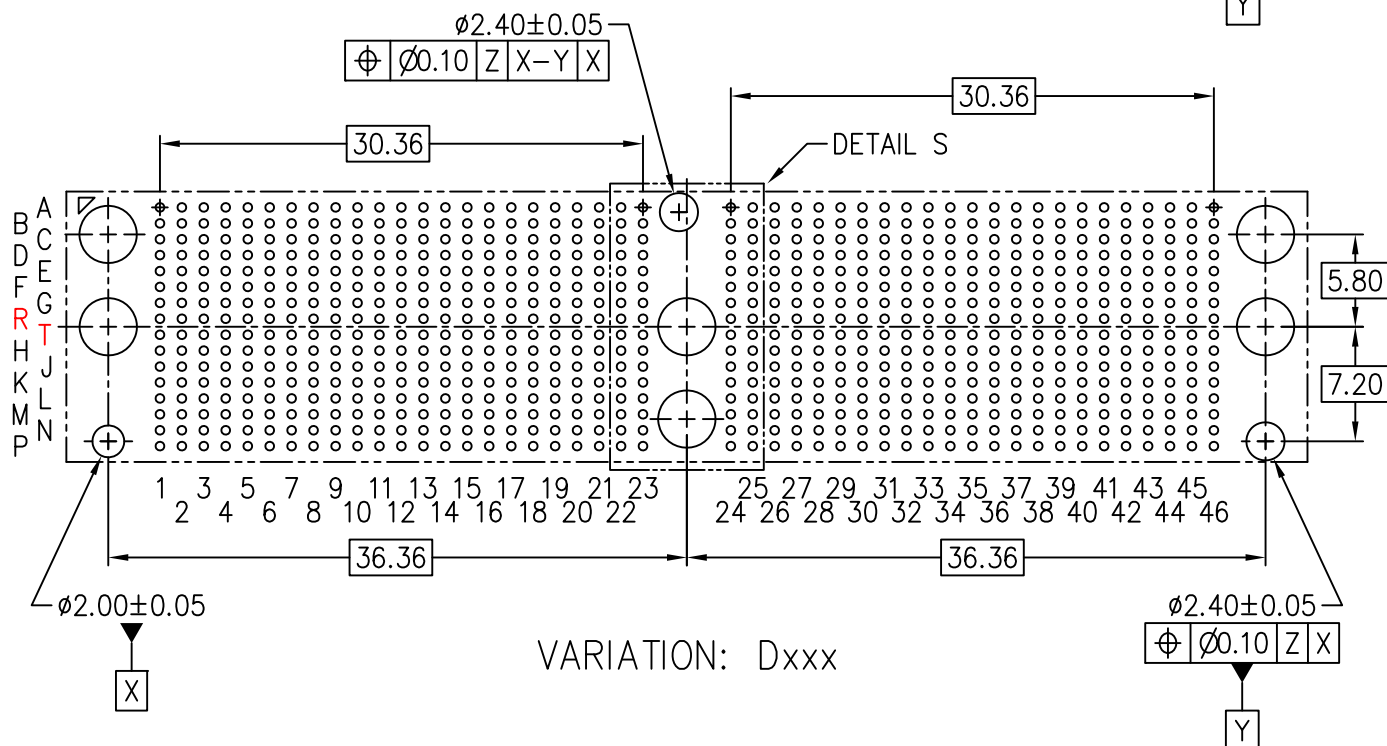
10. REFERENCE HOST BOARD FOOTPRINT (APPLY TO VARIATION: Bxxx ONLY). CONNECTOR PIN SHALL LAND ON THE PAD BEFORE AND AFTER DEFLECTION DURING THE ASSEMBLY.



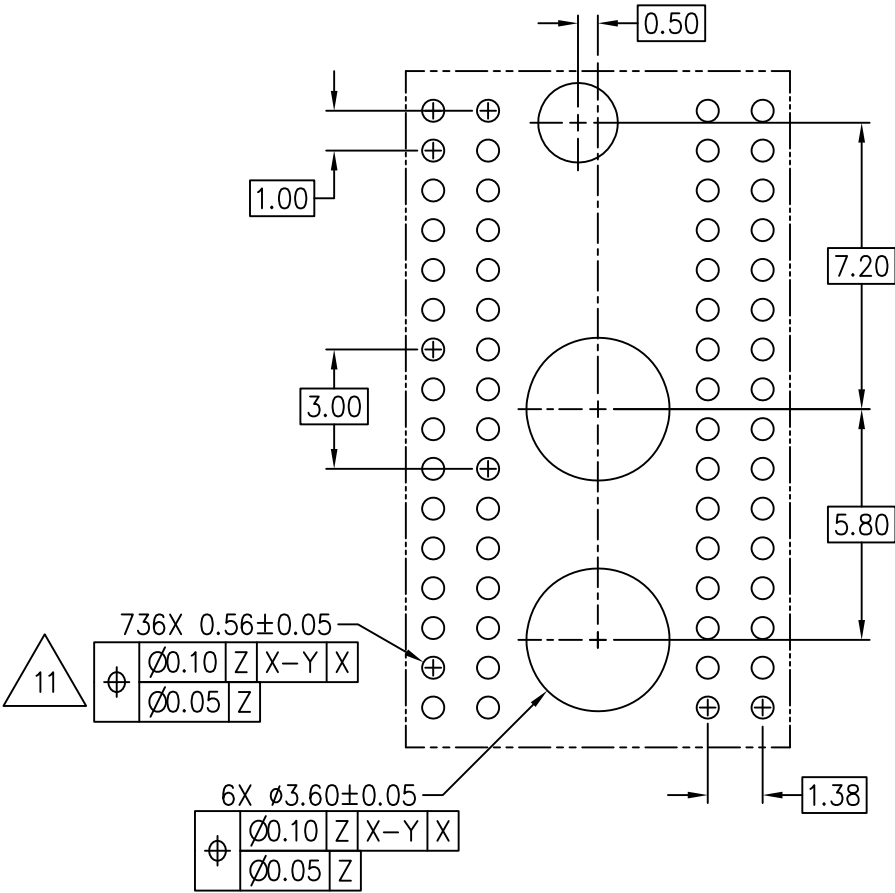
DETAIL R
DATUM Z: HOST BOARD SURFACE

	HOST BOARD CONTACT PAD FOR CONNECTOR PIN SHAPE A.
	HOST BOARD CONTACT PAD FOR CONNECTOR PIN SHAPE B.

-
- Technical drawing of a rectangular plate with a grid of holes. The plate has overall dimensions of 100.00 x 100.00. The grid consists of 46 columns and 12 rows of holes. The holes are arranged in a staggered pattern. The drawing includes various dimension lines and callouts. A central section is labeled 'DETAIL S'. The drawing is labeled 'VARIATION: Cxxx'.



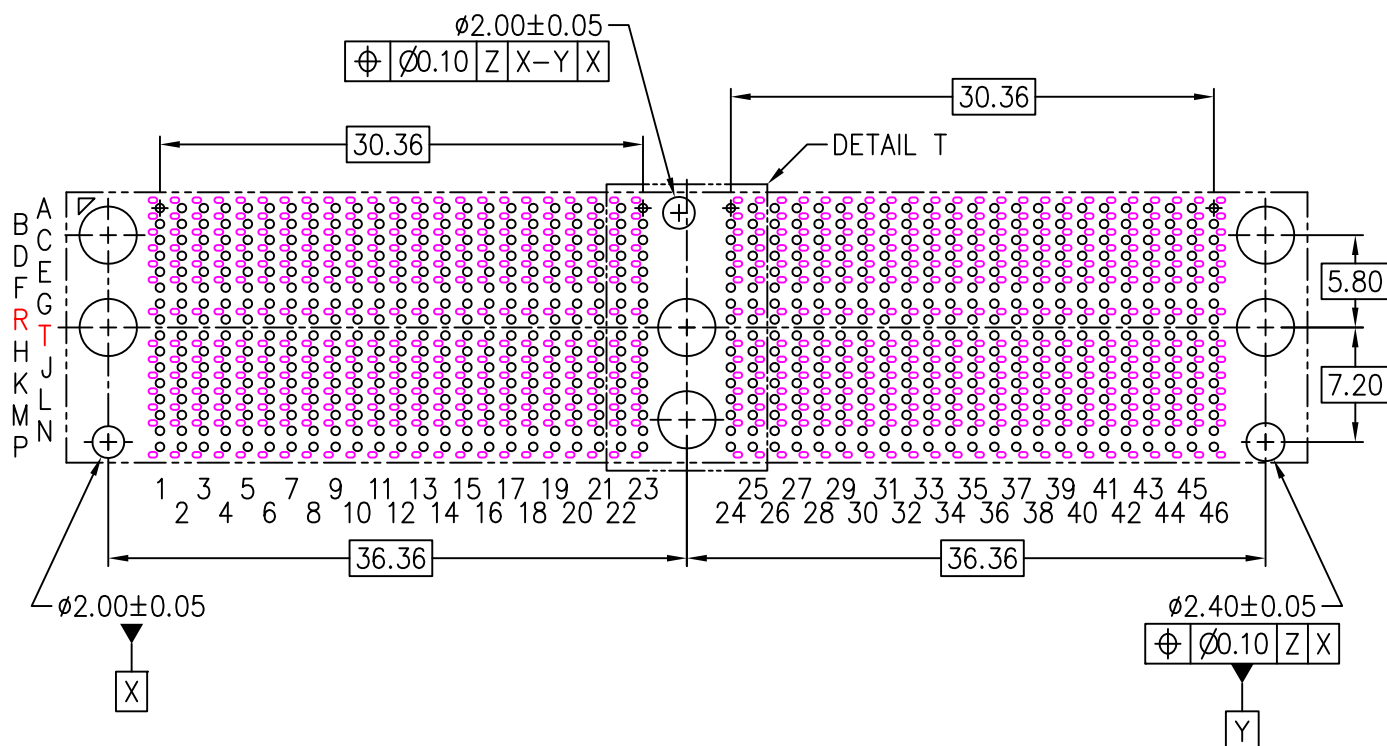
NOTES CONTINUED:



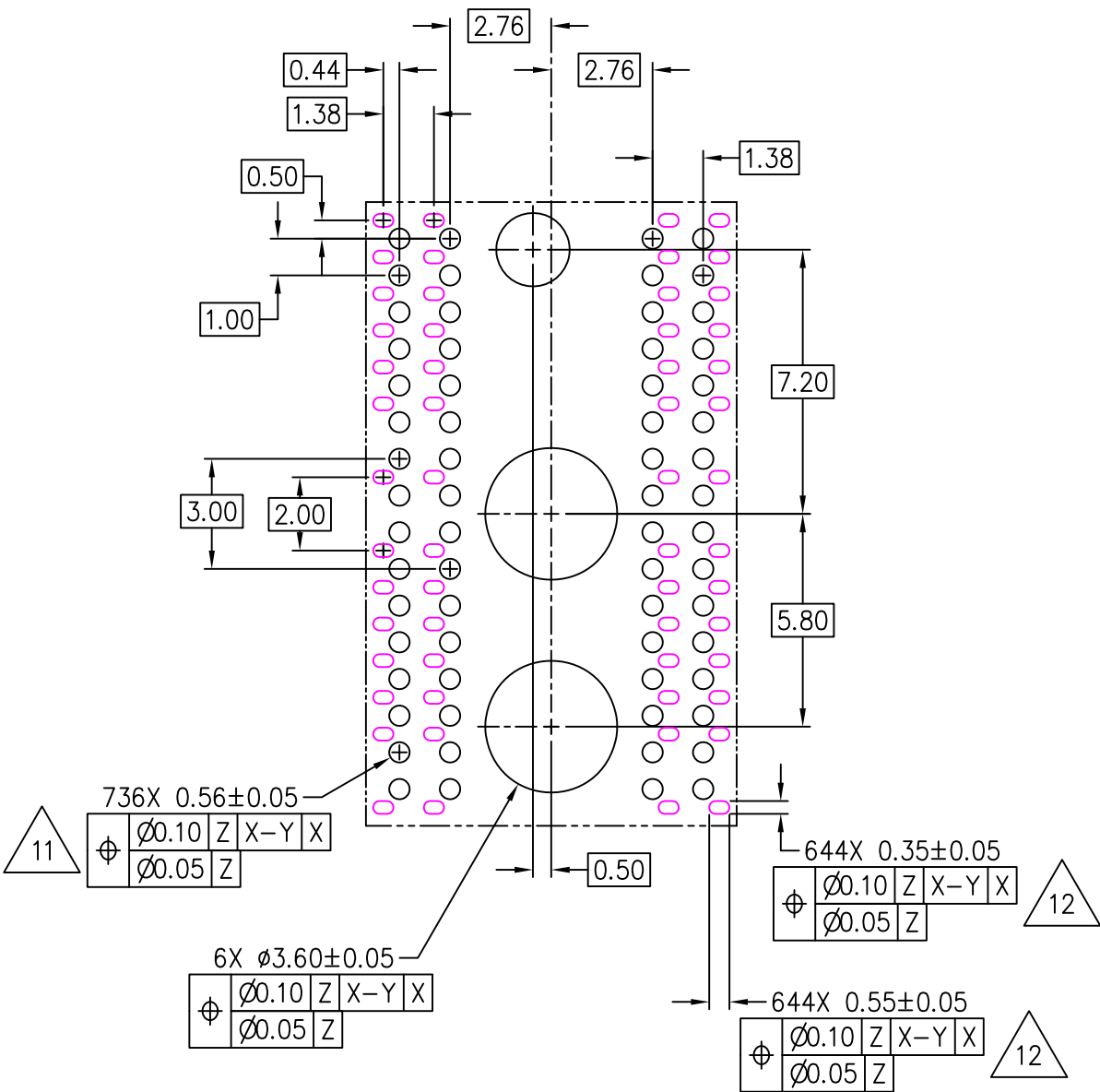
DETAIL S
DATUM Z: HOST BOARD SURFACE

NOTES CONTINUED:

14. REFERENCE HOST BOARD FOOTPRINT (APPLY TO VARIATION: Axxx AND Cxxx). CONNECTOR PINS SHALL LAND ON THE PAD BEFORE AND AFTER DEFLECTION DURING THE ASSEMBLY.



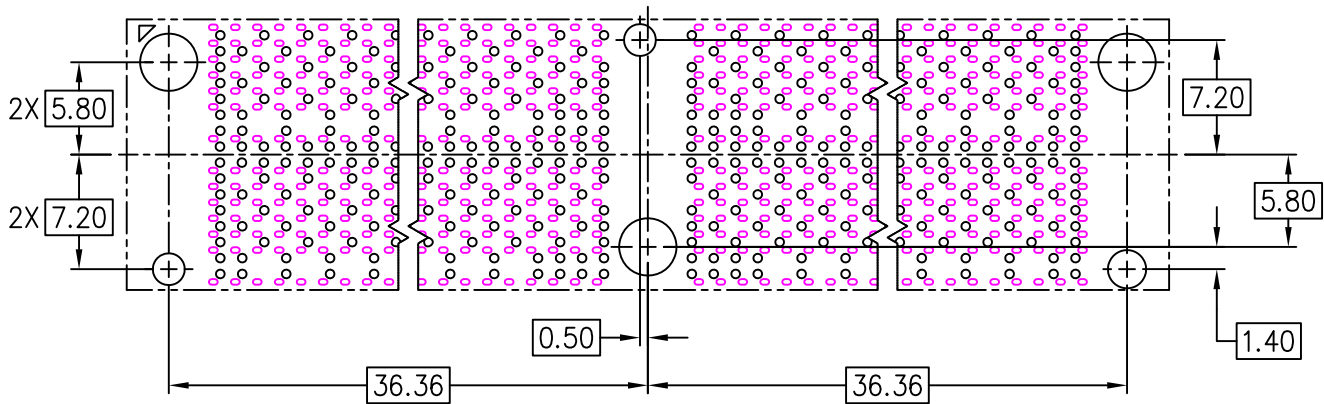
NOTES CONTINUED:



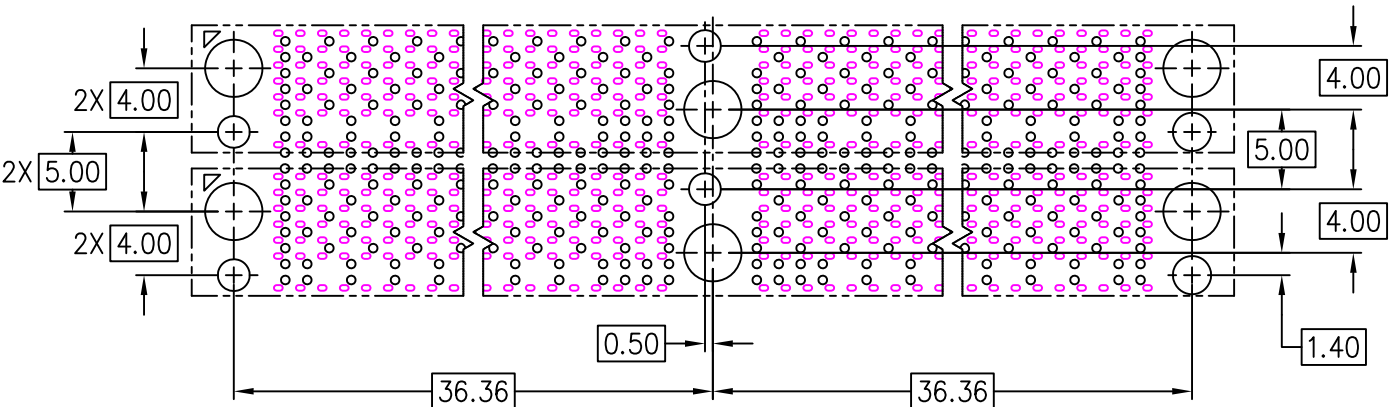
DETAIL T
DATUM Z: HOST BOARD SURFACE

APPLICATION NOTES:

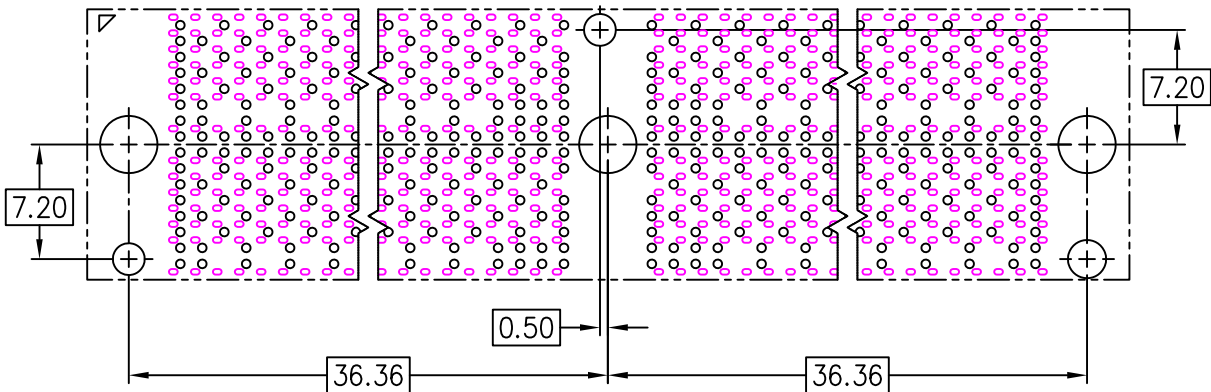
15. REFERENCE HOST BOARD LAYOUT (VARIATION Axxx ONLY AND DDR5 APPLICATION).



16. REFERENCE HOST BOARD LAYOUT (VARIATION Axxx, Bxxx AND DDR5 APPLICATION).

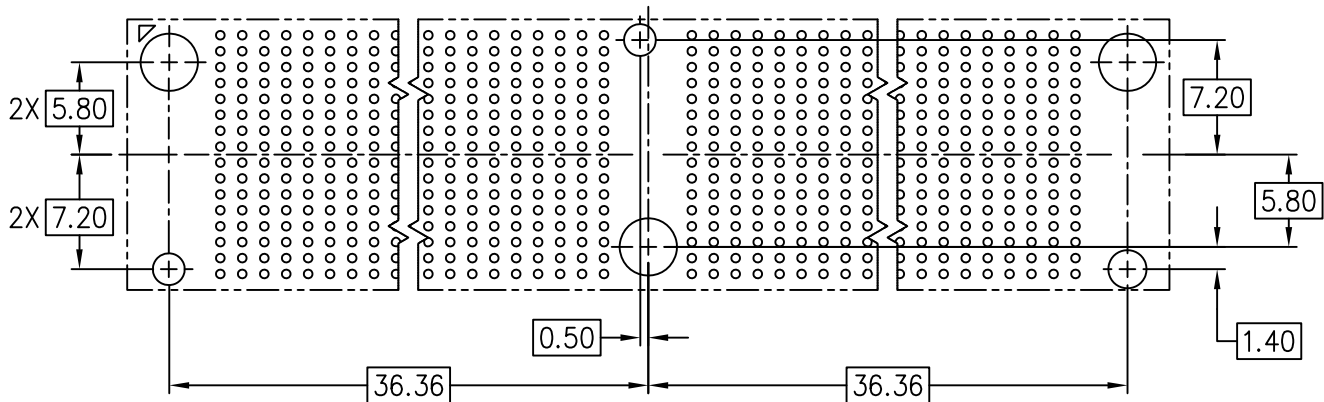


17. REFERENCE HOST BOARD LAYOUT (VARIATION Axxx ONLY AND LPDDR5 APPLICATION).

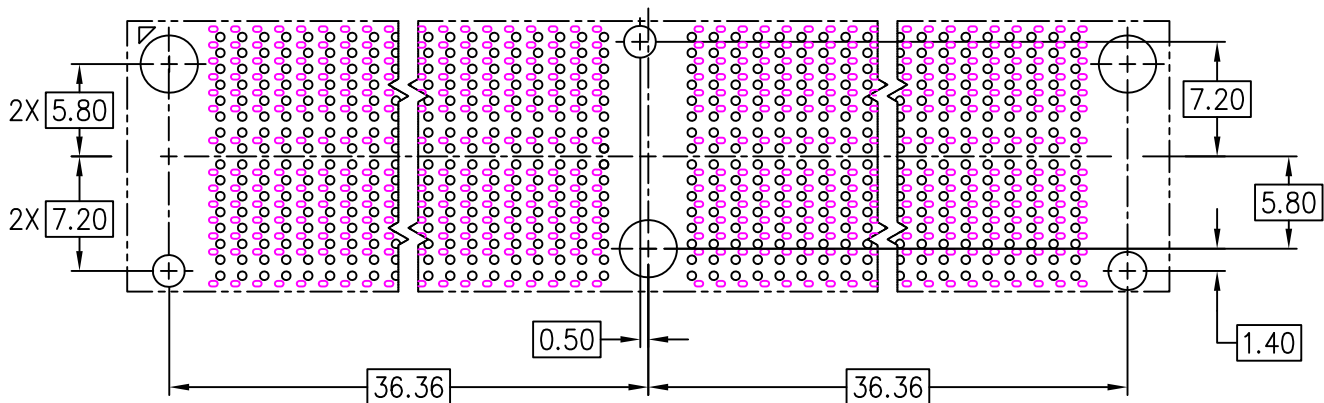


APPLICATION NOTES CONTINUED:

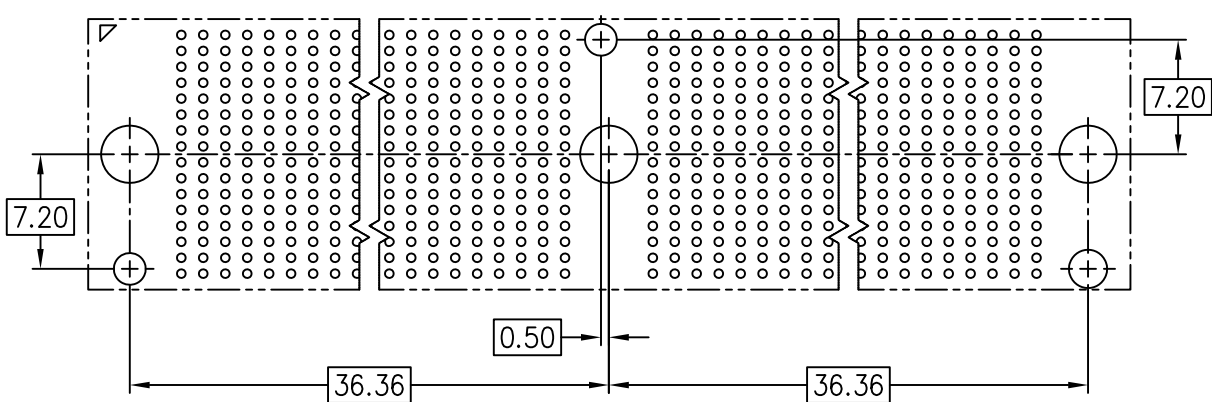
18. REFERENCE HOST BOARD LAYOUT (VARIATION Cxxx ONLY; DDR5 APPLICATION).



19. REFERENCE HOST BOARD LAYOUT (COMBINATION OF VARIATION Axxx AND VARIATION Cxxx; DDR5 APPLICATION).

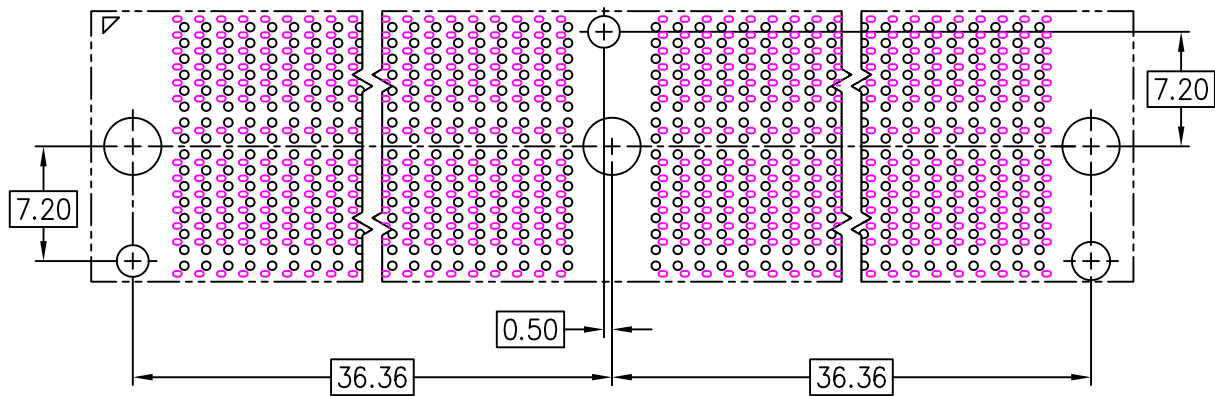


20. REFERENCE HOST BOARD LAYOUT (VARIATION Cxxx AND Dxxx ONLY; LPDDR5 APPLICATION).

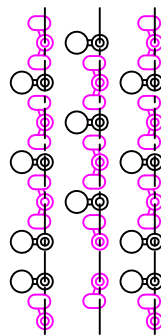


APPLICATION NOTES CONTINUED:

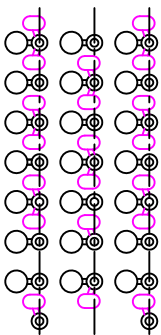
21. REFERENCE HOST BOARD LAYOUT (COMBINATION OF VARIATION Axxx AND VARIATION Cxxx/Dxxx; LPDDR5 APPLICATION).



22. REFERENCE NON-HDI HOST BOARD ROUTING AND VIA PLACEMENT.



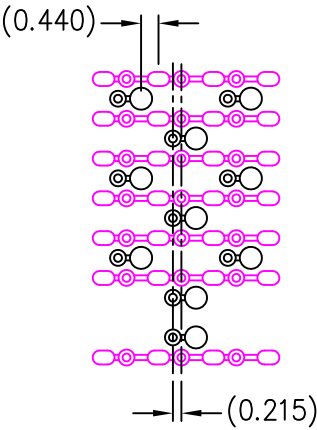
VARIATION:
Axxx OR Bxxx



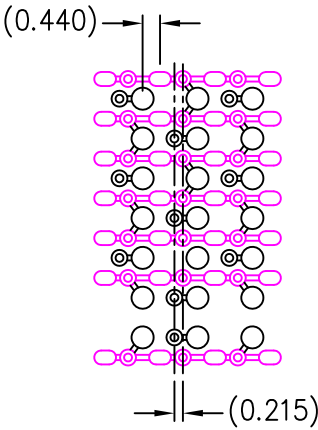
VARIATION:
Axxx AND Cxxx

OPTION 1
1:1 S/G VIA PATTERN
FOR MORE ROUTING SPACE

APPLICATION NOTES CONTINUED:

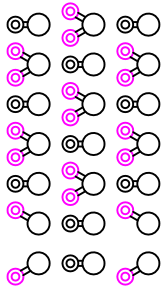


VARIATION:
Axxx OR Bxxx



VARIATION:
Axxx AND Cxxx

OPTION 2
1:2 S/G VIA PATTERN
FOR BETTER SIGNAL INTEGRITY



VARIATION: Cxxx AND Dxxx

OPTION 3
1:2 S/G VIA PATTERN FOR MORE ROUTING SPACE
AND BETTER SIGNAL INTEGRITY

APPLICATION NOTES CONTINUED:

23. THE CONNECTOR STAMPED TERMINALS MAY NEED TO BE SHUNTED UNDER THE DEFLECTED CONDITION TO MEET THE ELECTRICAL REQUIREMENTS. EITHER TOP OR BOTTOM PLATE MAY BE REQUIRED TO ENSURE RELIABLE RETENTION FOR SYSTEM APPLICATION.

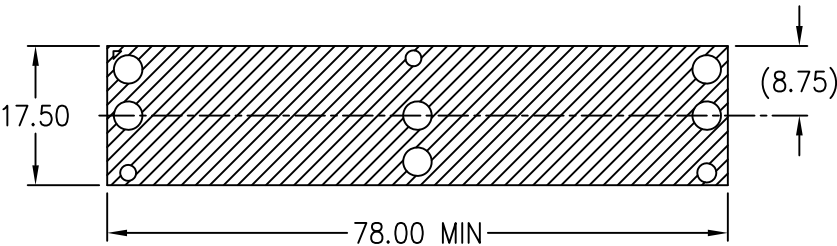


UNDEFLECTED

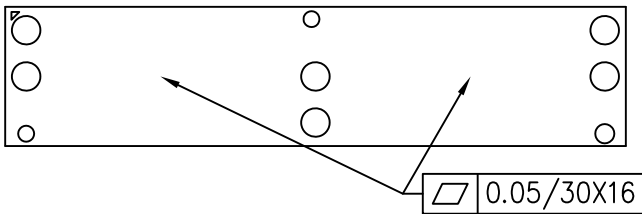


DEFLECTED

24. THE CONNECTORS MAY BE PACKED IN A TRAY. FOR DETAILS REFER TO JEDEC CO-040.
25. THE DIMENSIONS ENCLOSED IN PARENTHESES ARE FOR REFERENCE ONLY.
26. SOLDER MASK IS RECOMMENDED TO BE REMOVED IN THIS AREA ON THE TOP LAYER OF SYSTEM BOARD, WHERE THE CONNECTOR IS TO BE MOUNTED.



27. RECOMMENDED FLATNESS OF THE HOST BOARD, ONLY APPLY TO THE AREA WITH SURFACE TERMINAL (AKA. CONTACT PAD).



0.05/30X16

28. MATE WITH $\phi 2.40$ HOLE ON THE HOST BOARD.

STP (3D) FILE RECORD

3D FILE NAMES MAY EXCEED LENGTH REQUIREMENTS FOR SOME SOFTWARE TOOLS.

STP FILE NAME	DATE	ITEM NUMBER
SO-032A_PDUtBXC-H500_I0p5-R8p15x78p0Z2p9	JUL 2023	14-215
SO-032A_PDUtBXC-H500_I0p5-R8p15x78p0Z6p90	JUL 2023	14-215
SO-032A_PDUtBXC-H1000_I0p5-R17p15x78p0Z1p90	JUL 2023	14-215
SO-032A_PDUtBXC-H1000_I0p5-R17p15x78p0Z2p90	JUL 2023	14-215
SO-032B_PDUtBXC-H644_I1p0-R17p15x78p0Z1p05	NOV 2023	14-222
SO-032D_PDUtBXC-H736_I1p0-R17p15x78p0Z1p05	NOV 2024	14-231

TASK GROUP CONTRIBUTORS

ALIBABA(CHINA) CO. LTD
AMPHENOL CORPORATION
ARGOSY RESEARCH INC.
CHANGXIN MEMORY TECHNOLOGIES INC (CXMT)
DELL INC.
FOXCONN INTERCONNECT TECHNOLOGY
HEWLETT PACKARD ENTERPRISE
HP INC.
INTEL CORPORATION
LENOVO
LOTES CO., LTD
LUXSHARE-ICT, INC.
MICRON TECHNOLOGY INC.
MOLEX LLC
NEOCONIX, INC.
SAMSUNG SEMICONDUCTOR
SHENZHEN DEREN ELECTRONIC CO. LTD.
SK HYNIX INC.
SMART MODULAR TECHNOLOGIES INC.
TE CONNECTIVITY
WLCO SHENZHEN CO., LTD.

CHANGE RECORD

IF THE CHANGE INVOLVES ANY WORDS ADDED OR DELETED (EXCLUDING DELETION OF ACCIDENTALLY REPEATED WORDS), THE CHANGE IS TO BE INCLUDED BELOW. PUNCTUATION CHANGES MAY OR MAY NOT BE INCLUDED.

INITIAL ISSUE:A	DATE: JULY 2023	ITEM NUMBER:14-215
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CHANGE RECORD HISTORY:

INITIAL ISSUE:B	DATE:NOVEMBER 2023	ITEM NUMBER:14-222
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LOCATION	CHANGED FROM:	CHANGED TO:
SHEETS 1, 2 & 4		ADD DETAIL H
SHEET 5		NEW SHEET, ADDED OPTIONAL RECESSED CONTACT AREA
SHEET 7		ADDAED SECTION J-J
SHEET 8		ADDED DETAIL H
SHEET 8, TABLE 1	xDxx FROM: 6.80, 6.85, 6.90	xDxx TO: 7.45, 7.50, 7.55
SHEET 18, NOTE 20	DDR5	LPDDR5

ISSUE:C	DATE: JUNE 2024	ITEM NUMBER:14-227
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LOCATION	CHANGED FROM:	CHANGED TO:
SHEET 11, 12 & 16	5.52 BASIC	REMOVE DIMENSION: BASIC 5.52
		ADD DIMENSION: BASIC 2.76
SHEET 20		ADD NOTE 26
SHEET 21		ADD NOTE 27

ISSUE:D	DATE:NOVEMBER 2024	ITEM NUMBER:14-231
---------	--------------------	--------------------

LOCATION	CHANGED FROM:	CHANGED TO:
SHEETS 5 & 6		ADD VARIATION D
SHEETS 6 & 8		UPDATE SECTION J-J
SHEET 9		ADDED DETAIL K
SHEETS 10, 12-19	PCB	HOST BOARD
SHEETS 10, 11, 13-19		UPDATE FOOTPRINT BY ADDING ROW R AND T
SHEET 11	356X $\varnothing 0.56 \pm 0.05$	448X $\varnothing 0.56 \pm 0.05$
SHEETS 14 & 16	644X $\varnothing 0.56 \pm 0.05$	736X $\varnothing 0.56 \pm 0.05$

CHANGE RECORD

IF THE CHANGE INVOLVES ANY WORDS ADDED OR DELETED (EXCLUDING DELETION OF ACCIDENTALLY REPEATED WORDS), THE CHANGE IS TO BE INCLUDED BELOW. PUNCTUATION CHANGES MAY OR MAY NOT BE INCLUDED.

LOCATION	CHANGED FROM:	CHANGED TO:
SHEET 21	NOTE 27	ADD HOST BOARD FLATNESS RECOMMENDATION
SHEET 22, DELETED	NOTE 27 ON METAL VOID	REMOVED
SHEET 21		ADDED NOTE 28